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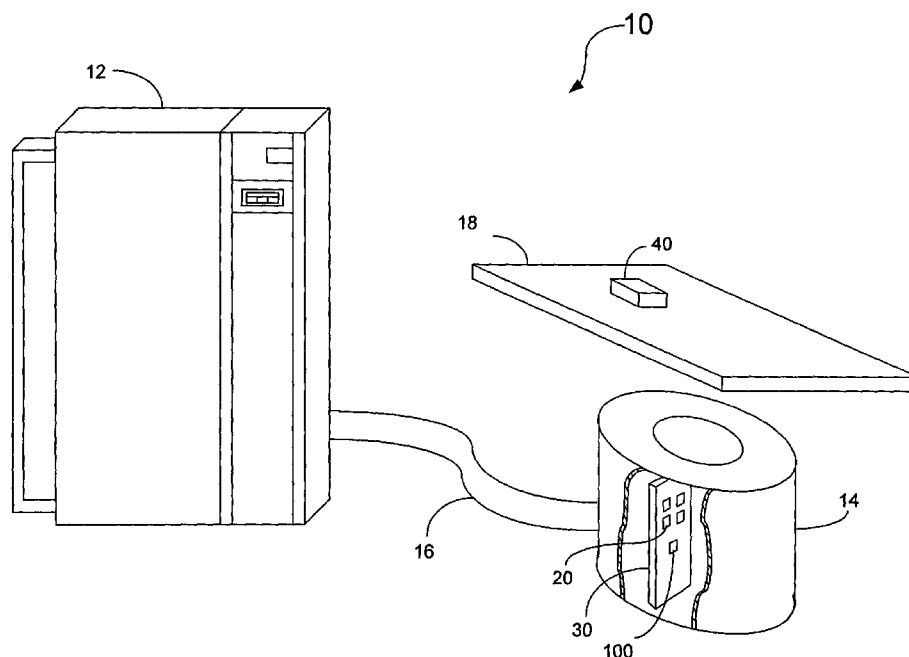
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(54) Title: METHOD AND APPARATUS FOR CALIBRATION AND VALIDATION OF HIGH PERFORMANCE DUT POWER SUPPLIES



(57) Abstract: A power supply circuit is disclosed for use with a semiconductor tester to power a device-under-test. The power supply includes power generation circuitry disposed in the tester to generate power for the device-under-test. Load circuitry is disposed within the tester and coupled to the power generation circuitry to selectively simulate the electrical loading of a device-under-test on the power supply.